

Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION (Use several sheets if necessary)	Docket No. H1823-00004	Serial No. 10/736,280
	Applicant: Che-Yu Li	
	Filing Date: 15 December 2003	Group Art <u>Unit</u> Unassigned

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U.S. PATENT DOCUMENTS

SEP 20 2004

*EXAM INER INITIA L	DOCUMENT NUMBER	DATE	NAME	OFFICE OF PETITIONS		FILING DATE IF APPROPRIATE
				CLASS	SUBCLASS	
HAL	3,354,260	November 1967	E. D. Brandt et al.			
	3,452,149	June 1969	F. J. Rinaldi			
	3,639,978	February 1972	Schurman			
	3,711,627	January 1973	Maringulov			
	3,800,378	April 1974	Lee et al.			
	4,781,640	November 1988	Tornoe et al.			
	6,298,551	October 2001	Wojnarowski et al.			
	6,312,266	November 2001	Fan et al.			
	6,663,399	December 2003	Ali et al.			
	6,695,623	February 2004	Brodsky et al.			
	6,712,620	March 2004	Li et al.			
	US 0221/0024735	September 2001	Kuhlmann-Wilsdorf et al.			
	US 2002/0106913	August 2002	Schuenemann et al.			
HAL	US 2003/0049974	March 2003	Bauer et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATIO N	YES	NO

OTHER (Including Author, Title, Date, Pertinent Pages, Etc.)

HAL	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN; <i>Interposer Carrier</i> ; January 1987; pp3678 – 2680
HAL	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN; <i>Improved Interconnection Structure</i> ; November 1988; pp17 – 19

EXAMINER <u>HAL Phu</u>	DATE CONSIDERED <u>12/15/05</u>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.	

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✓ M.L	US 2003/0176083	September 2003	Li et al.	✓	✓	
	US 2003/0207608	November 2003	Weiss	✓	✓	
	US 2004/0053519	March 2004	Li et al.	✓	✓	
	US 2003/0073329	April 2003	Beaman et al.	✓	✓	
✓ M.L	US 2003/0134525	July 2003	Sweetland et al.	✓	✓	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	YES	NO

OTHER (Including Author, Title, Date, Pertinent Pages, Etc.)

✓ M.L	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN, <i>Special Thermal Conductive Interposers</i> , September 1993
✓ M.L	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN; <i>High Density Area Array Connector</i> ; April 1991; Pub. No. 324
EXAMINER ✓ M.L	DATE CONSIDERED 12/15/03

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<p>Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION (Use several sheets if necessary)</p> <p style="text-align: center;">SEP 10 2004 U.S. PATENT AND TRADEMARK OFFICE</p>	Docket No. H1823-00004		Serial No. 10/736,280
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OTHER (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>PhL</i>	Solid State Technology; <i>Integrating Backend Processes</i> ; February 2001; pp78 - 85
	HCD, Inc.; <i>Two Fundamental Approaches to Enabling High Performance LGA Connections</i> ; pp508 - 514
	HDC, Inc.; <i>An Adaptable, High Performance LGA Connector Technology</i>
	Internet page of Tecknit Interconnection Products; <i>Standard Fuzz Button Contacts</i>
	Internet page of Tecknit Interconnection Products; <i>Fuzz Button Contacts</i>
	Internet page of Cinch; <i>High-Speed Interconnect Technology</i>
	Internet page of COSMOS; <i>COSMOS helps analyze circuit board connectors</i>
	HDC, Inc.; <i>SuperButton Land Grid Array (LGA) Connectors</i> ; 6/2003
	Internet page of Design News.com; <i>PC-nonlinear FEA makes the connection</i> ; John Lewis; September 18, 2000
	A High Density Ian Grid Array Connector for MCM's; M. E. St. Lawrence and S. S. Simpson pp1491 - 1511
	International Symposium on Microelectronics; <i>Z-Axis Interconnection for 3-D High Density Packaging</i> ; S. Spiesshoefer et al.; pp167 - 171
	HDC; <i>Corporate Overview</i> ; June 2003
	A novel Elastomeric Connector for Packaging Interconnections, Testing and burn-in Applications; D. Y. Ehih et al.
<i>PhL</i>	Button Contacts for liquid Nitrogen Applications; Frank Almquist
EXAMINER <i>PhL</i>	DATE CONSIDERED <i>12/17/05</i>
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